



INFOTECH  
automation

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**INFOTECH**  
automation

**2024**

**INFOTECH**

# COMPANY PRESENTATION



- 1 COMPANY OVERVIEW
- 2 PRODUCTS
- 3 APPLICATION EXAMPLES

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# WHAT WE DO

**Infotech designs, produces and delivers high accuracy positioning systems for the automatic execution of precision processes – from stand alone machines to entire assembly lines**

**Infotech Component Matrix with more than 1000 modules**

**PLATFORMS – HEAD- / TABLE- / FEEDING-PERIPHERALS**

**100% DEVELOPMENT IN SWITZERLAND**

**95% PRODUCTION IN SWITZERLAND**

**> 2280 INSTALLATIONS WORLDWIDE**

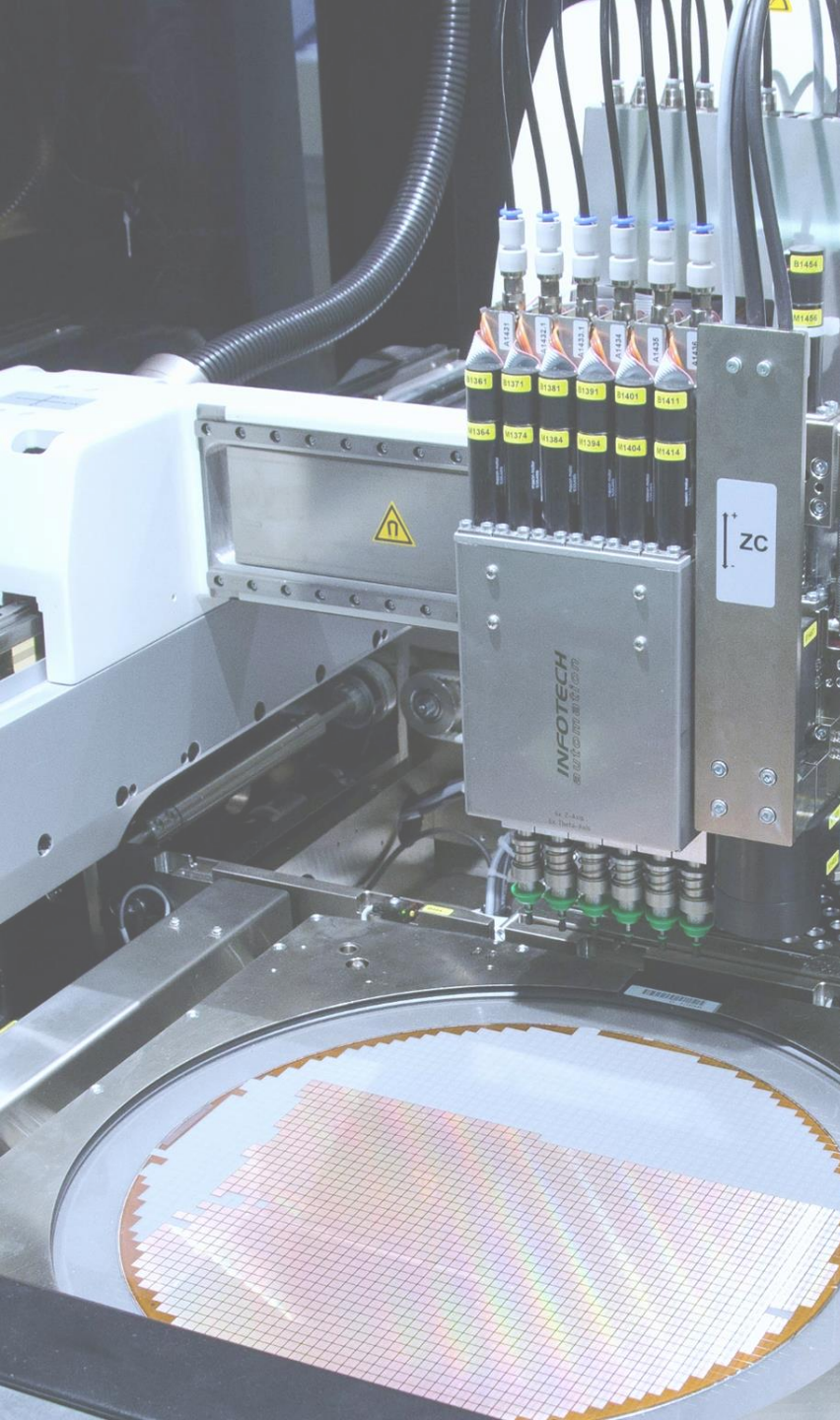






## HISTORY IN BRIEF

- Technical oriented company with headquarter in Solothurn Switzerland
- Founded 1984, in business for 40 years with 197 employees
- Internationally operating company providing total assembly line solutions to selected customers
- Almost 40 years of experience in providing automation software, engineering and process development for semiconductor- and electronic hybrid manufacturing processes
- Since 2007 optimizing power module manufacturing processes - allowing total line solutions



## STRATEGY

- Analyzing the customers process requirements and generate an optimized concept together
- Configuring a total solution based on the Infotech component matrix which is adding value and is reducing the total cost of ownership for the lifetime of the production equipment or the production line
- Focusing on selected customers planning early and treating the supplier on a fair bases, understanding that their products can be produced more efficient, in higher quality and repeatability, more dynamic and more flexible – resulting with lower cost of ownership using Infotech products

# INFOTECH IN BRIEF

**100%**

Development at  
Infotech

**>95%**

Production in  
Switzerland

**40**

Years  
Infotech AG

**>2280**

Installations  
worldwide

**1056**

Years of experience  
in automation

**197**

Employees

**>40**

Support engineers  
worldwide

**>50%**

Engineers

**>20**

Countries



# HISTORY

Company registration

1984

Desktop, Component Matrix

2001



Production lines

2007

First pharma assembly line

2015



Hybrid Bonder: Die Bonding and SMD assembly

2020

>2'280 systems delivered

Diverse Buffer modules

2023

1999

Repositioning Infotech AG in Solothurn Switzerland



2003

Production cells



2009

Fully automatic watch assembly lines

2017

Fully automatic Power Module production line with 12" Wafer Bonder



2021

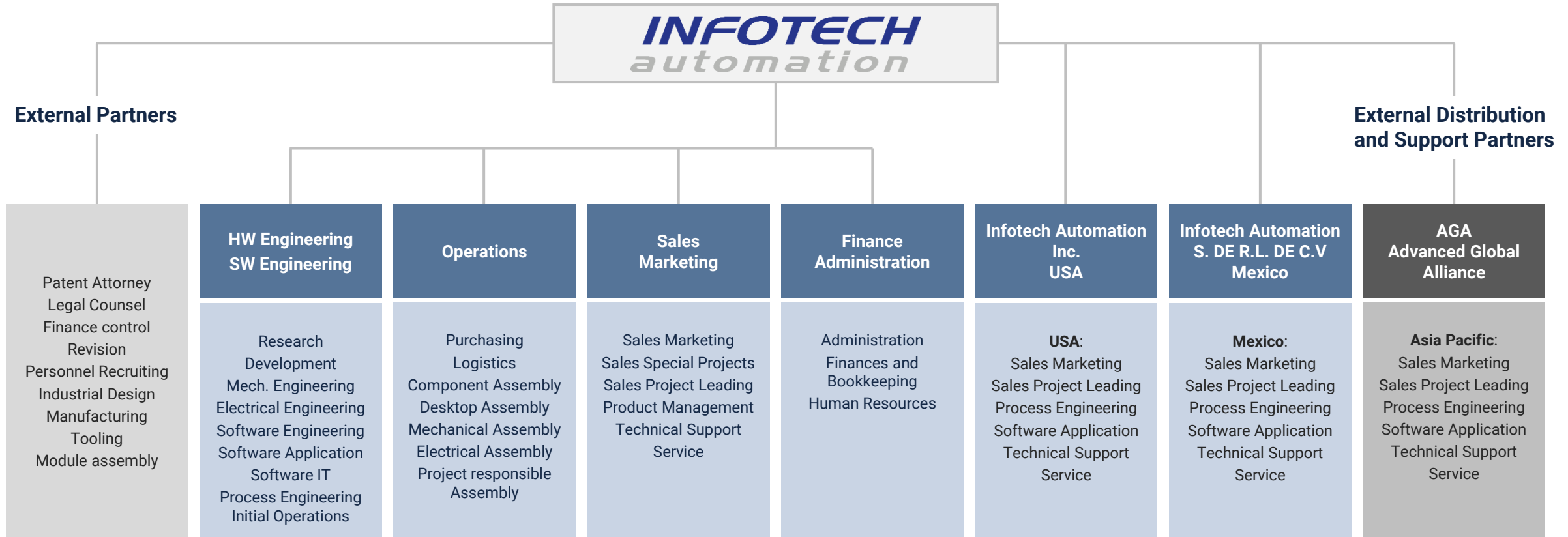
3D printing system for multimaterial designs



2023

Foundation of Infotech Automation Inc, USA

# ORGANIZATION



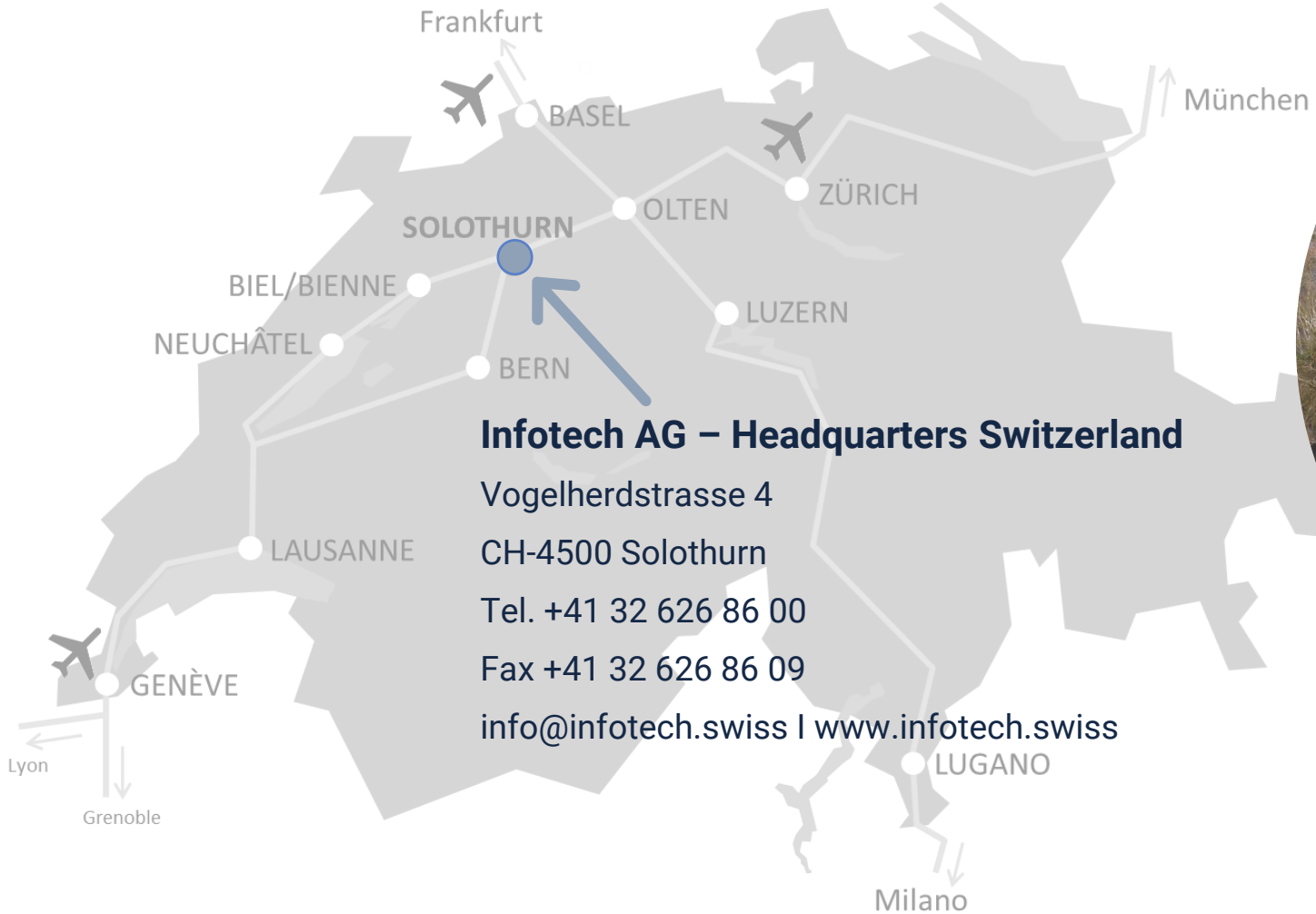
**External Partners:**  
 Activities with external companies and suppliers in the region of Solothurn

**Technology partners:**





# LOCATION HEADQUARTERS SWITZERLAND



## Infotech AG – Headquarters Switzerland

Vogelherdstrasse 4

CH-4500 Solothurn

Tel. +41 32 626 86 00

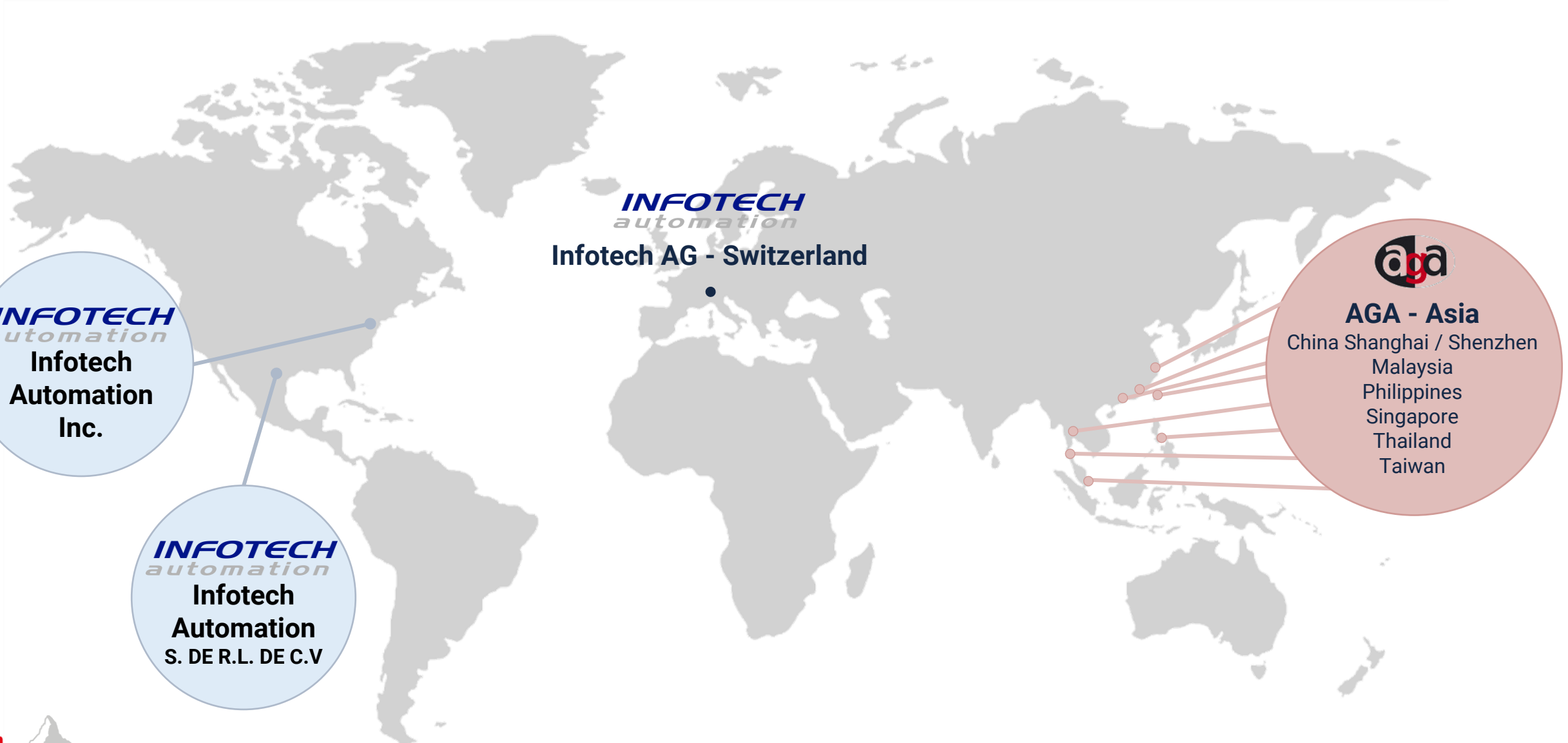
Fax +41 32 626 86 09

info@infotech.swiss | www.infotech.swiss





# INTERNATIONAL LOCATIONS



# REFERENCES



**2024**

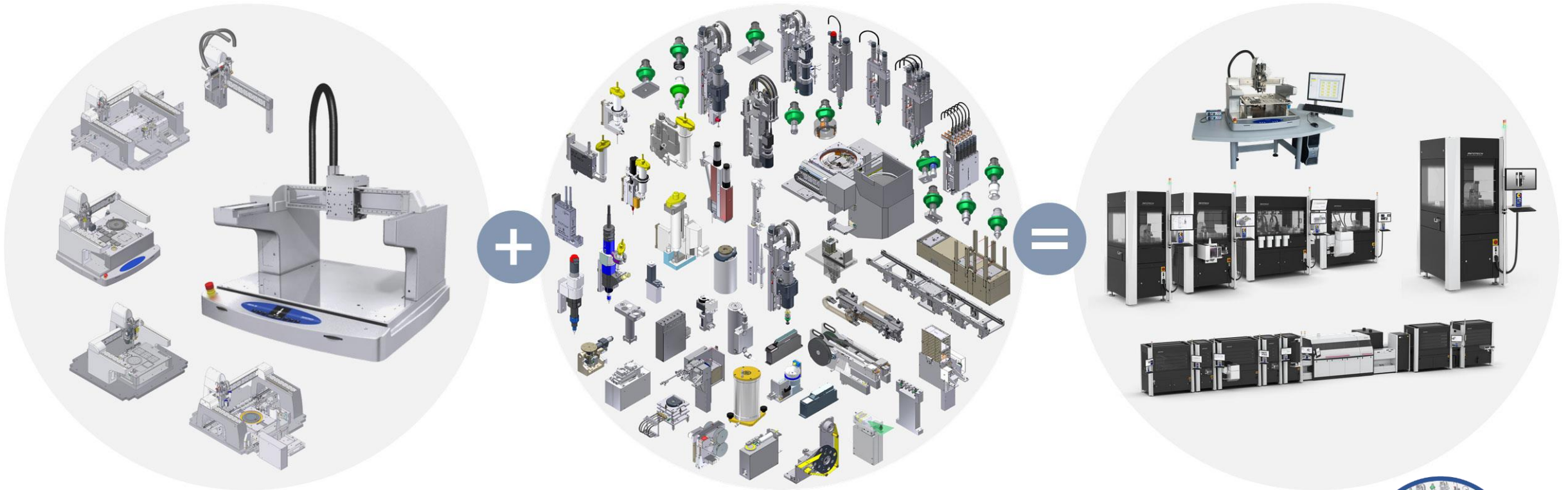
**INFOTECH**

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# INFOTECH COMPONENT MATRIX

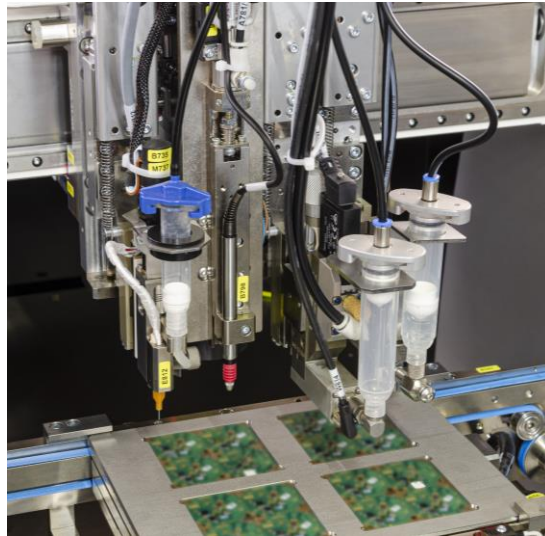




# INFOTECH COMPONENT MATRIX



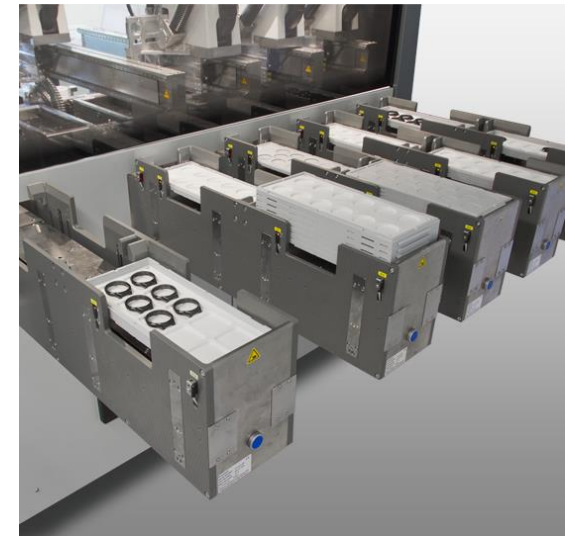
**PRODUCTION CELLS  
PLATFORMS**



**HEAD PERIPHERALS**



**TABLE PERIPHERALS**



**FEEDING PERIPHERALS**



# PRODUCTION CELLS

IC-900, IC-1200, IC-1600, IC-1800, IC-2000 and IC-2200



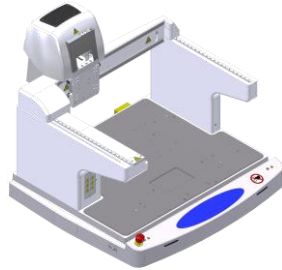


# PLATFORMS

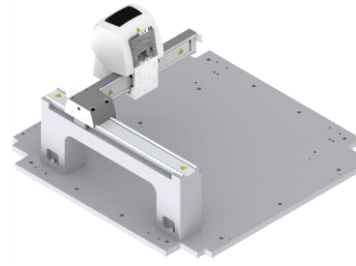
IP-100



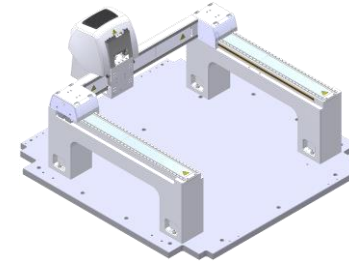
IP-500



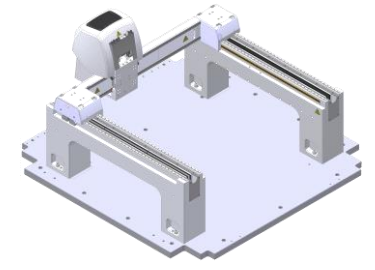
IP-600



IP-620



IP-720



Travel range X 93 – 140 mm

400 mm

210 – 340 mm

210 – 540 mm

210 – 540 mm

Travel range Y 440 – 680 mm

400 mm

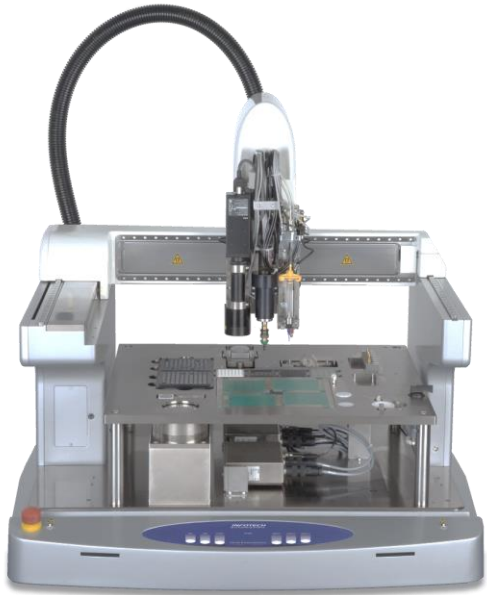
400 – 730 mm

400 – 730 mm

540 – 730 mm

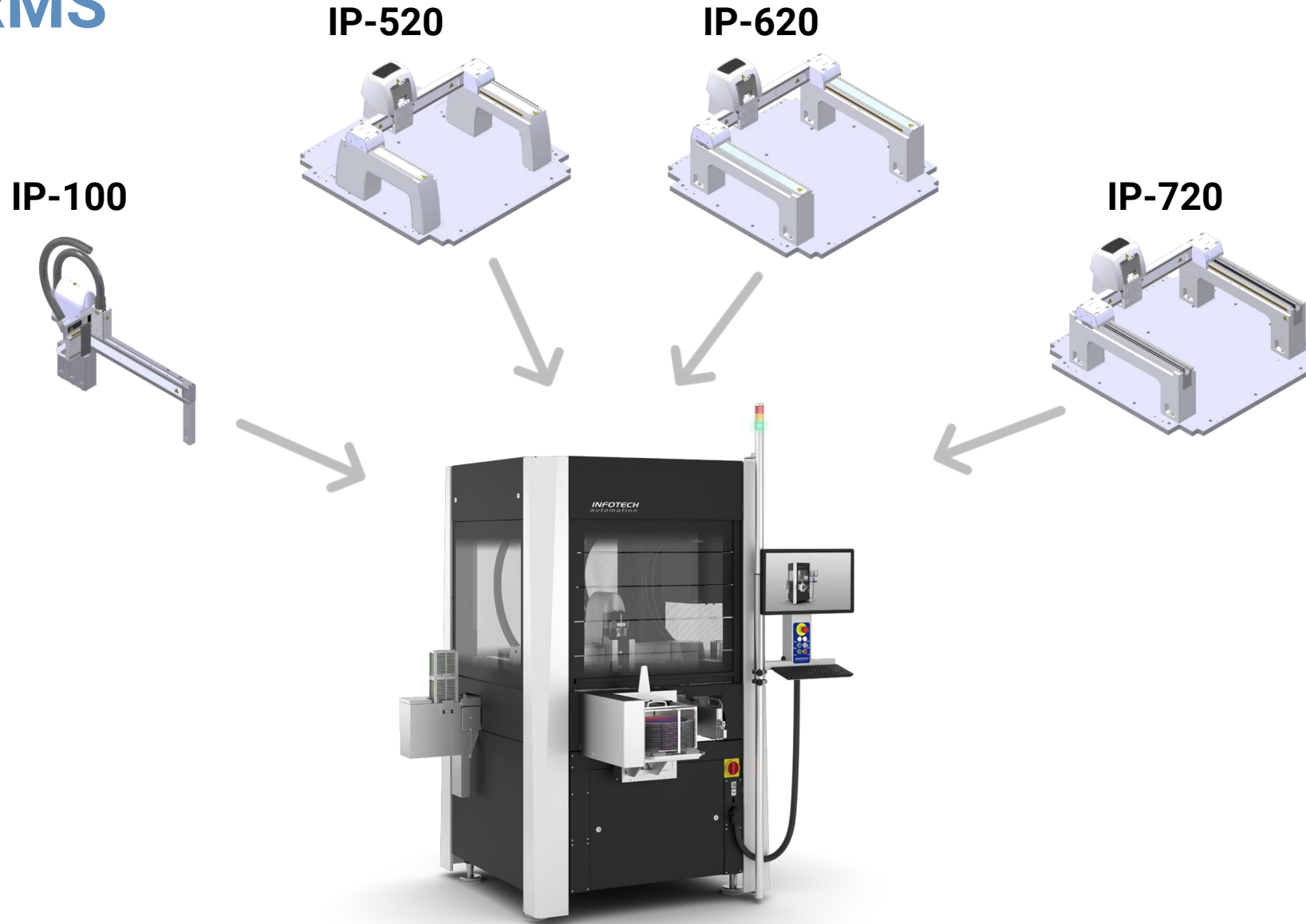


# PLATFORMS



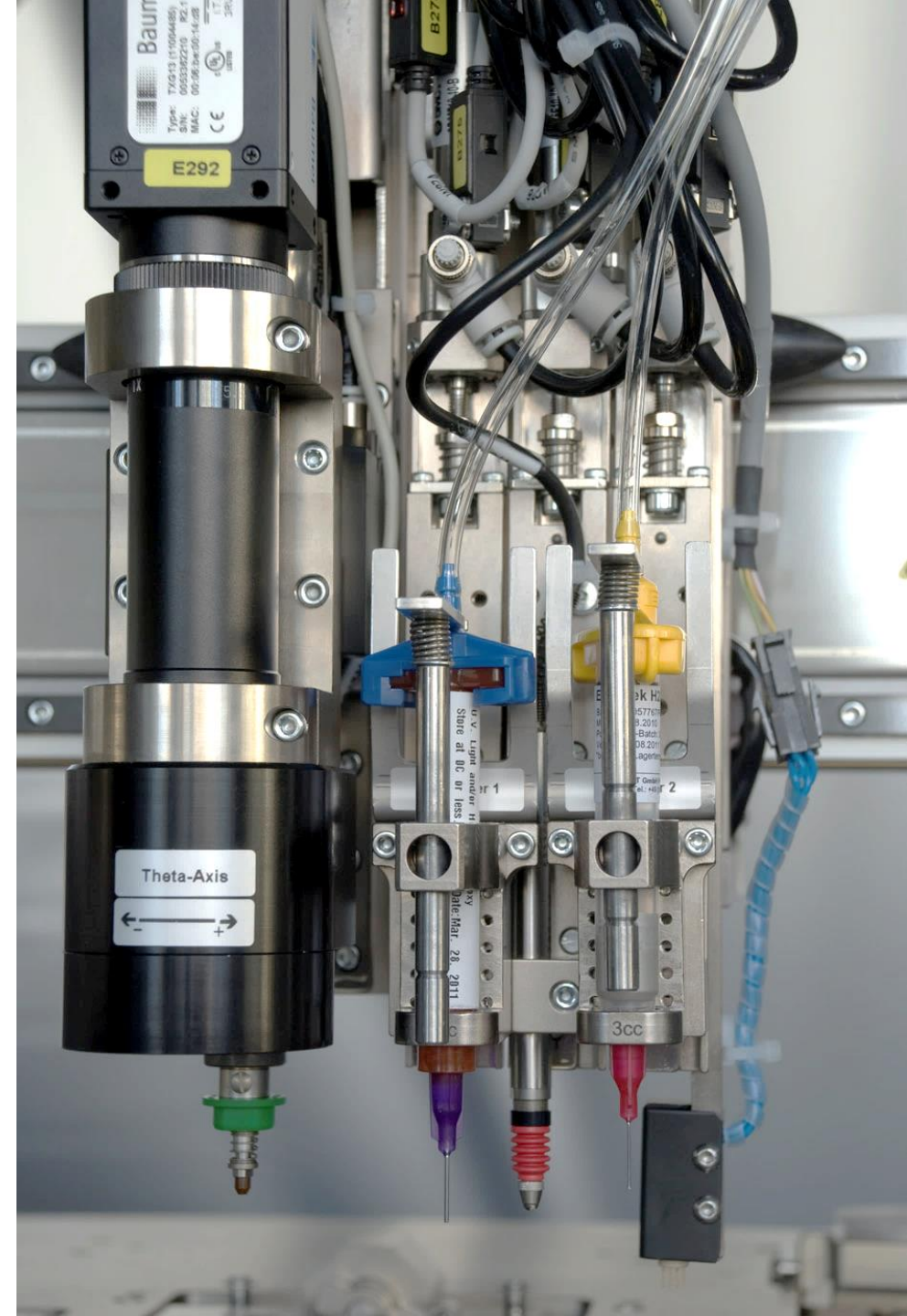
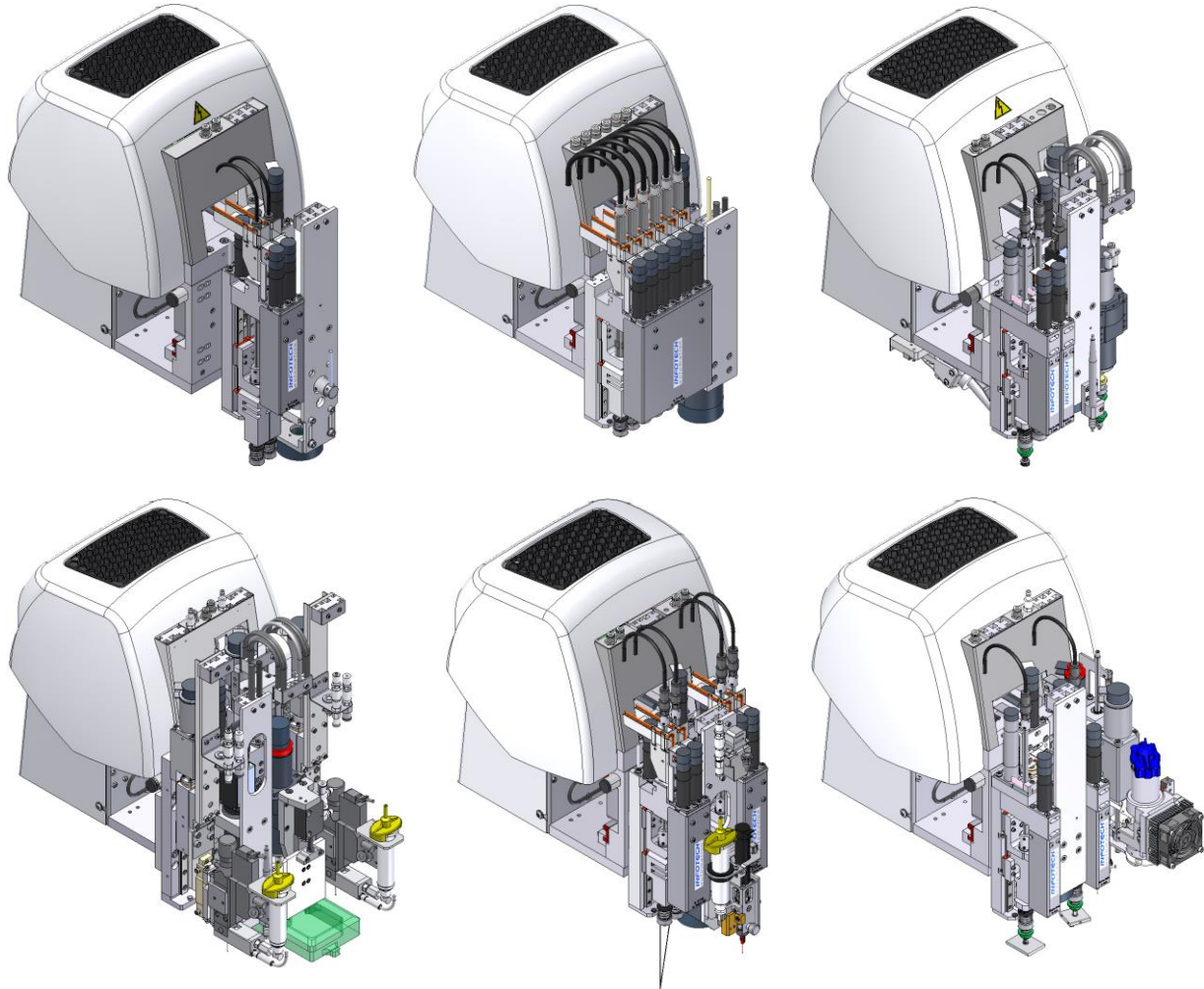
**Scalable from Desktop to Production Line**

# PLATFORMS



PRODUCTS

# HEAD PERIPHERALS













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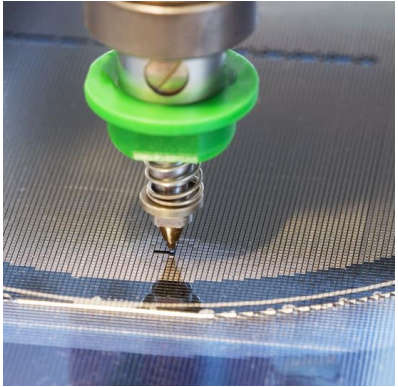
**INFOTECH**

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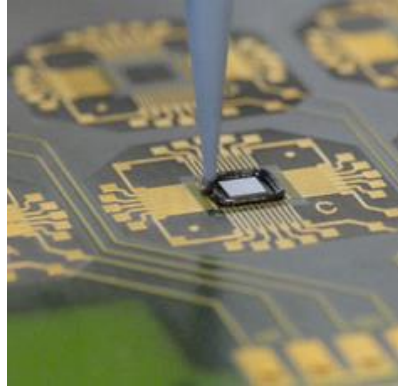


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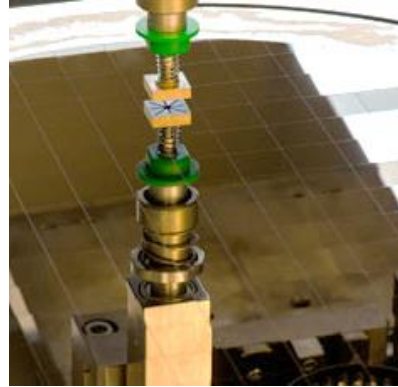
# APPLICATIONS



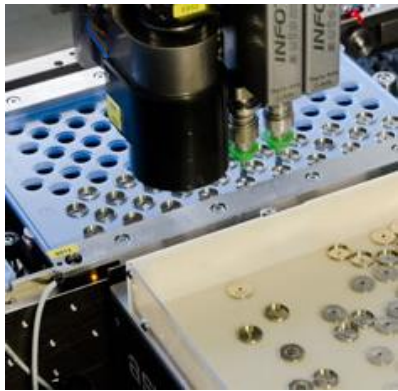
**ASSEMBLING**



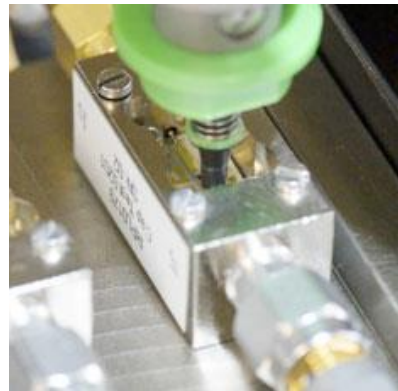
**DISPENSING**



**POWER MODULE**



**SORTING**



**TESTING**



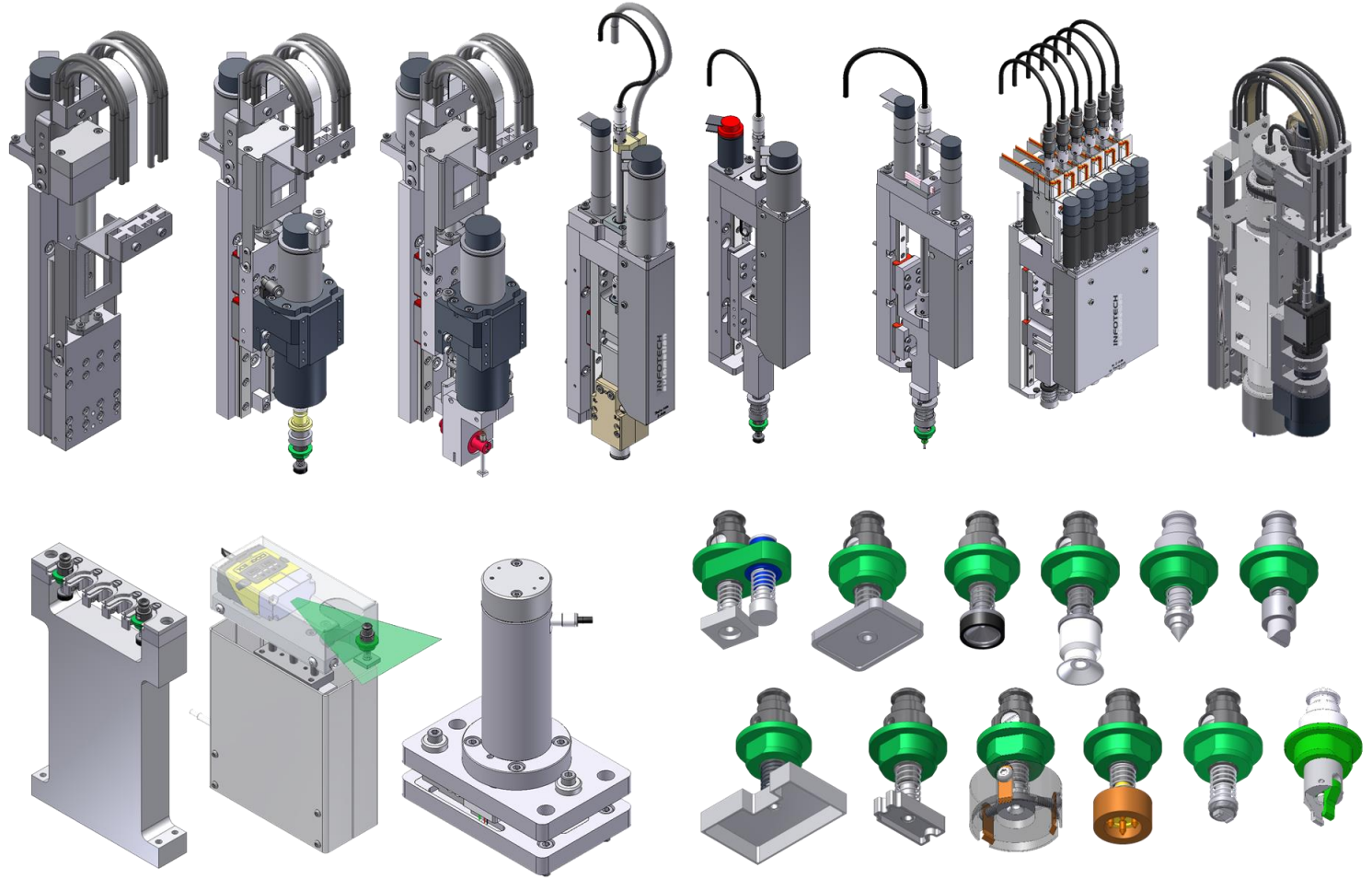
**PACKAGING**



APPLICATION EXAMPLES

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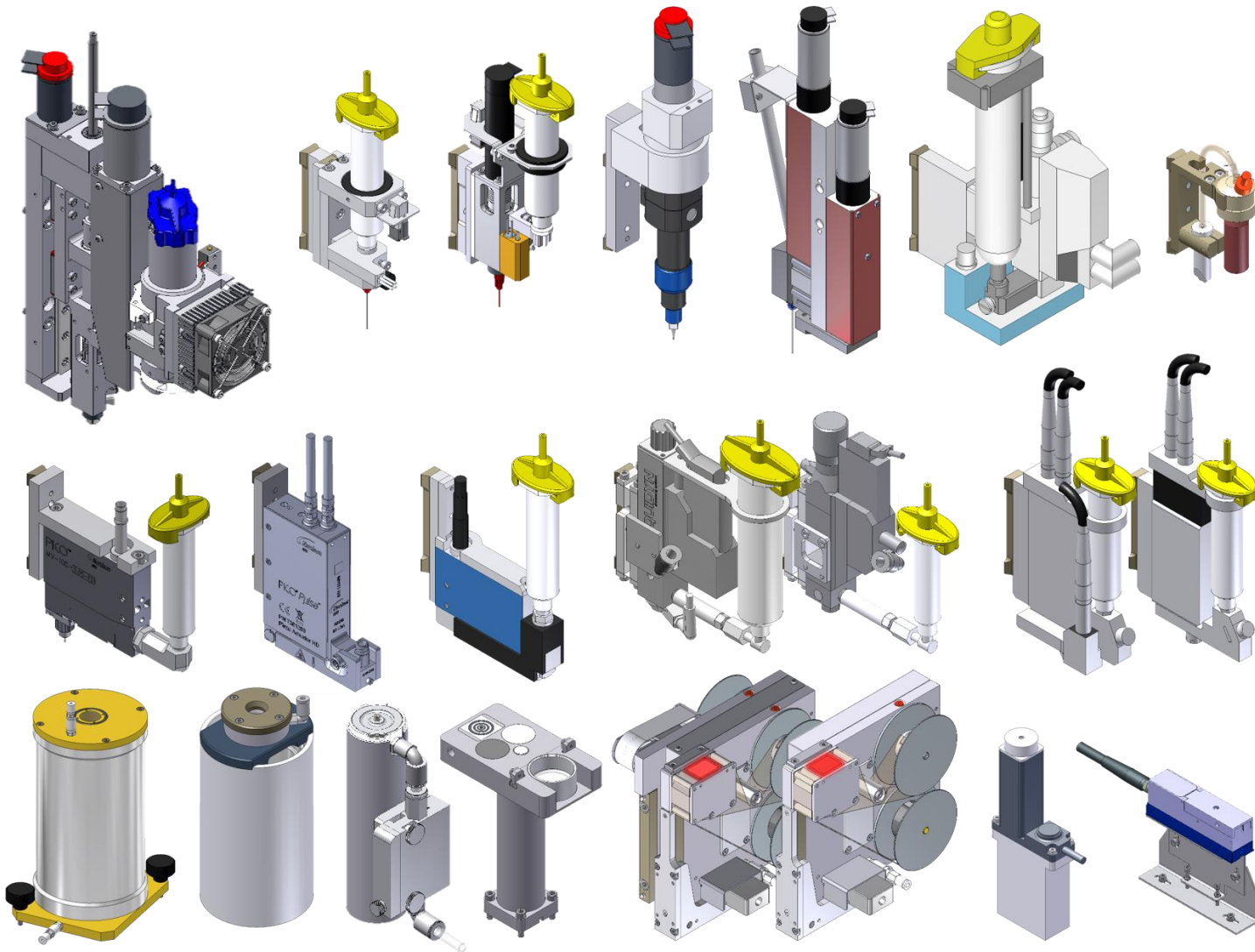
# ASSEMBLING





APPLICATION EXAMPLES

# DISPENSING



# IP-500 DESKTOP

Relative assembly of opto electric transceivers

Relativbestückung von optoelektronischen Transceivern





# IP-500 DESKTOP

Dispense-and assembly processes for pressure sensors

Dosier- und Bestückungsprozesse für Drucksensoren





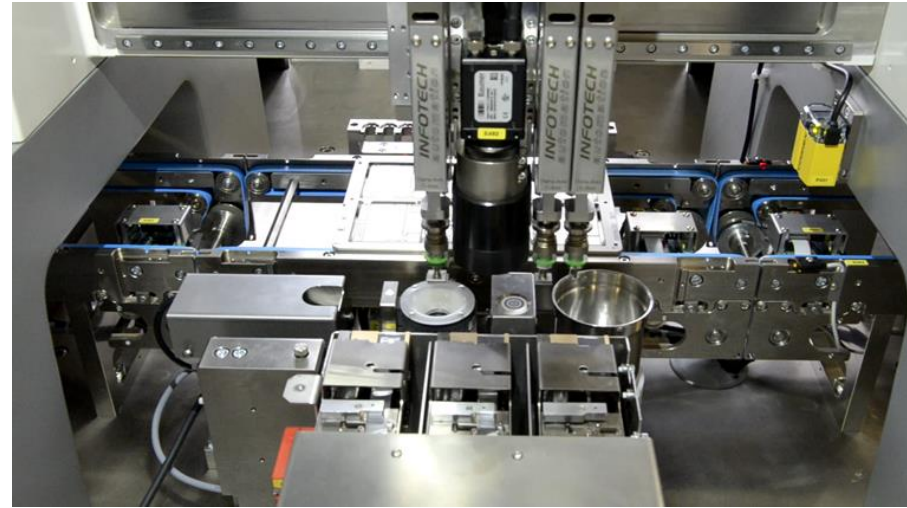
# IP-500 DESKTOP

Pre-assembly of optical parts for  
solid-state laser

Vorbestückung von optischen  
Teilen für Festkörperlaser



# IC-900 PREFORM BONDER



IC-900 Preform bonder with 3 preform feeders  
PF2-14 - Cut, pick, inspect and place solder  
preform from tape onto DBC-substrates for  
power modules

IC-900 Lötfolien Bonder mit 3 Lötfolienzuführungen  
PF2-14 Schneiden, aufnehmen, Qualitätskontrolle  
und absetzen der Lötfolie auf eine DCB-Substrat für  
die Leistungselektronik

# IC-900 DISPENSER



Using the IC-900 Dispenser, dispense applications can be processed precise, efficient and repeatable. With the Infotech designed universal dispense valve interface, several different dispense pumps can be exchanged quickly.

# IC-1200 – DIE BONDER 12" WAFER



Preform and die bonder for power module production with 12" Wafer die eject feeder

Lötfolien und Die Bonder für die Produktion von Modulen für die Leistungselektronik mit 12" Wafer Zuführung und Ausstecheinheit

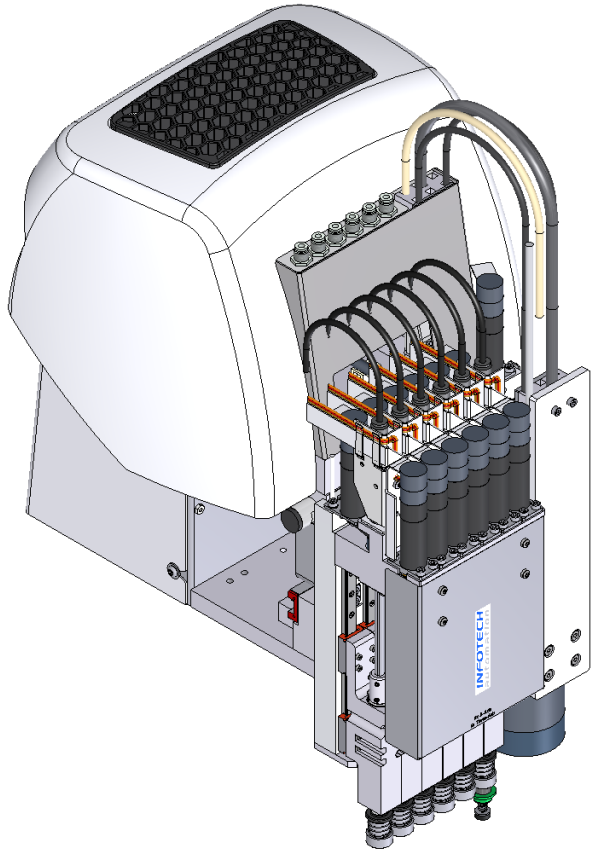


# IC-2200 – DUAL DIE SINTER BONDER 12" WAFER



Dual Sinter Bonder with dual 12" Wafer die eject feeder and die tacking process peripherals

# IC-2000 - POWER MODULE BONDER 12" WAFER

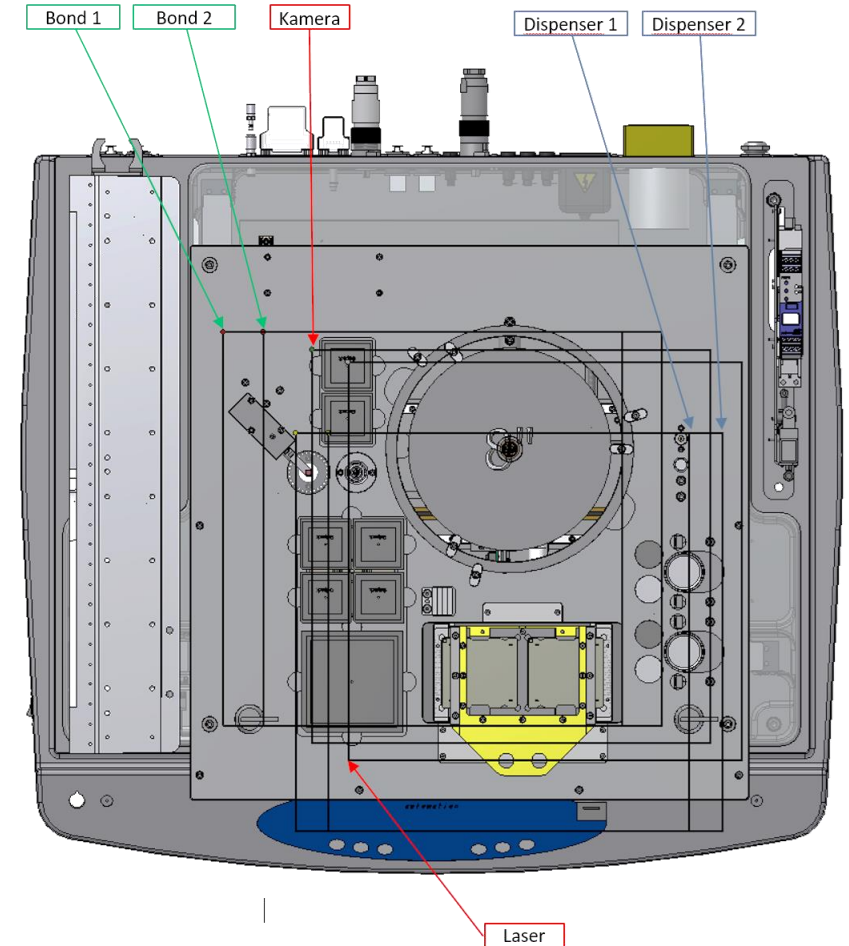
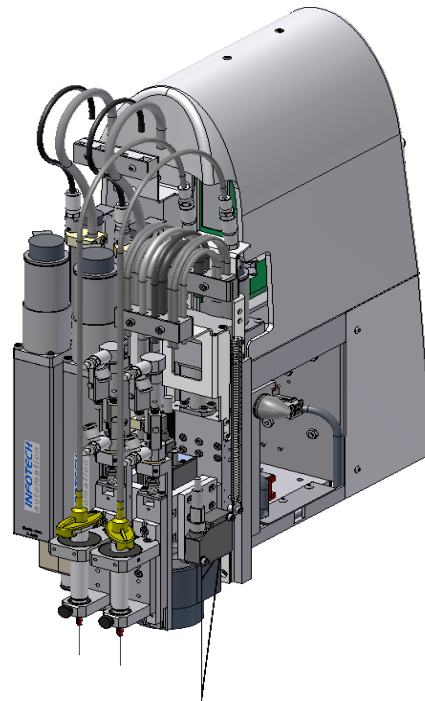
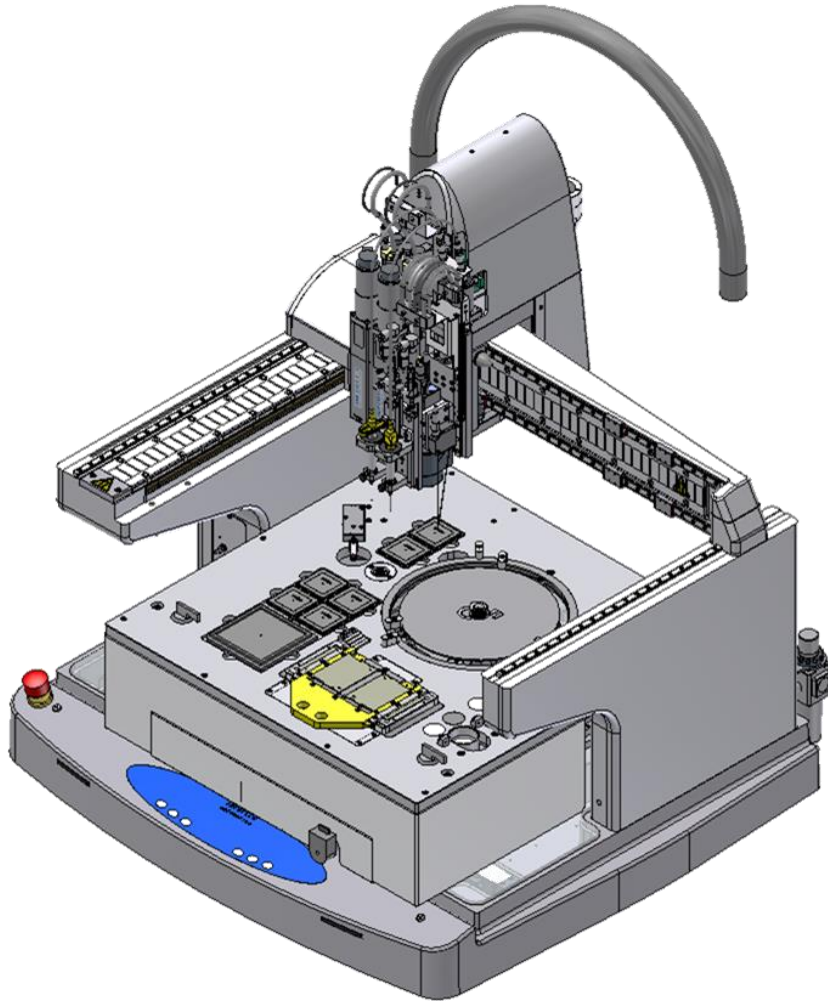


High-speed die bonder for power module production with 12" Wafer die eject feeder and six independent assembly heads

Lötfolien und Die Bonder für die Produktion von Modulen für die Leistungselektronik mit 12" Wafer Die-Eject Zuführung und sechs unabhängigen Bestückungsköpfen

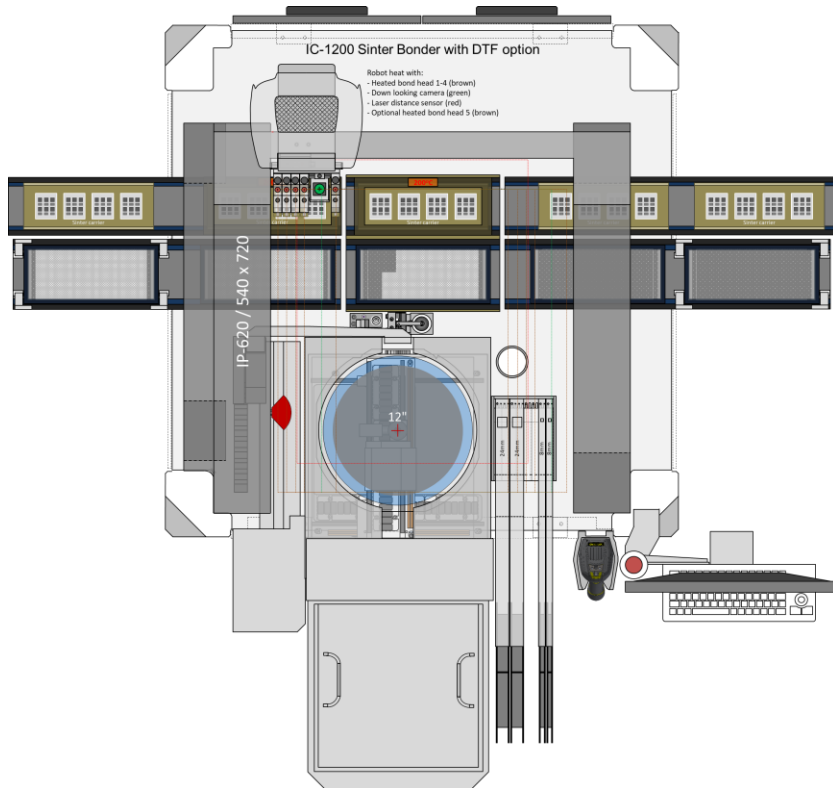


# DIE ATTACH FOR SINTER PRODUCTS- LAB EQUIPEMENT





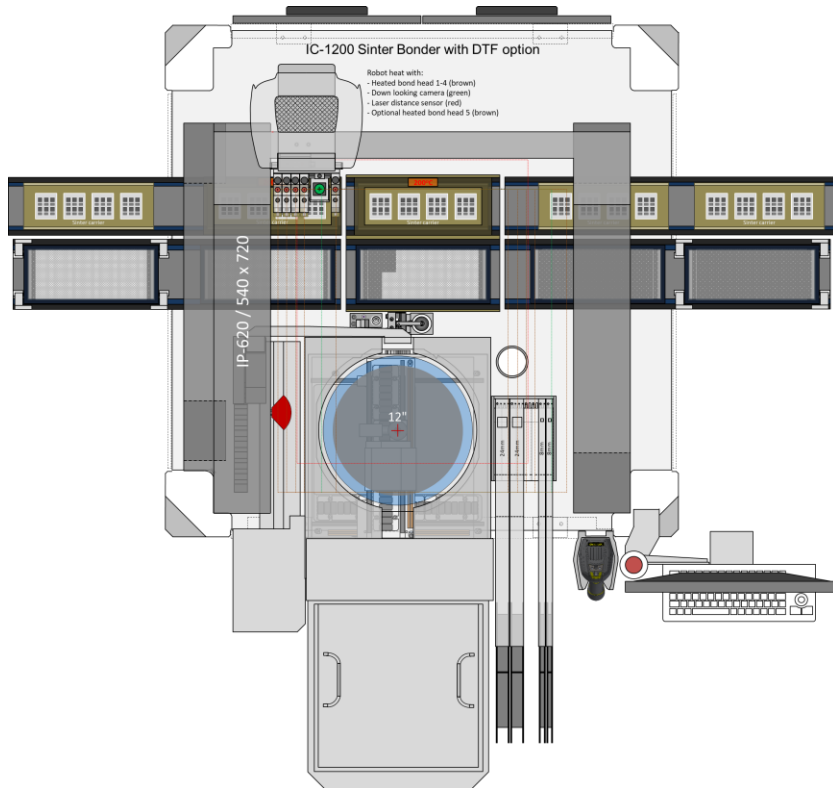
# DIE ATTACH FOR SINTER PRODUCTS



- Heated bond heads up to 3 x 34 mm width heads, or up to 5 x 20 mm heads
- Heated bond head up to 300°C, with manual exchangeable heater bond head tools with bond force capabilities up to 300N
- Optional assembly head with interposer to transfer Die from cold to heated bond head
- Substrate holder plate with manual tilt adjustment, heated surface up to 300°C with integrated force sensor table
- Substrate pre-heat station, heated surface up to 300°C
- Die-, Preform-, Spacer-, DTS-, NTC-, SMD Bonder with sinter tacking option
- Wafer-, Preform-, Tape-, Waffle pack-, loose parts- Feeder
- Dispenser, Flipper, Dip-station and many other options from the Infotech component matrix
- Tacking process into sinter paste, DTF-Process or wafer laminated processes

The highly flexible Die attach power module bonder is used for various production demands from laboratory up to series production.

# DIE ATTACH FOR SINTER PRODUCTS



## DTF with Tacking process

Supports DTF process (Die Transfer Film - Alpha Assembly Solutions) from 4x4" size, Jedec size or wafer frame size

- Loading and pre-heating substrates
- Die recognition on wafer / waffle pack / Tape (ink dot, alignment) using upper vision, or using wafer map
- Pickup Die with heated bond head
- Transfer film to Die with force feedback
- Die alignment and quality inspection of sinter foil on Die using lower vision
- Verify substrate temperature
- Tack on heated substrate with heated bond head and force sensing
- Unloading of substrates

The highly flexible Die attach power module bonder is used for various production demands from laboratory up to series production.

# IC-1800 CHAIN ASSEMBLY



## Chainsaw Bosch

Sorting of 4 parts building the chain, assembly, 3D-inspection and grouting of chain

## Bosch Kettensäge

Sortieren von 4 Teilen zur Montage der Kette, bestücken, visuelle 3D- Kontrolle, und verpressen der Teile zur Kette





# IC-1200



## Pharma assembly line:

3X IC-1200 / 2x IP-520 / 4x IP-100

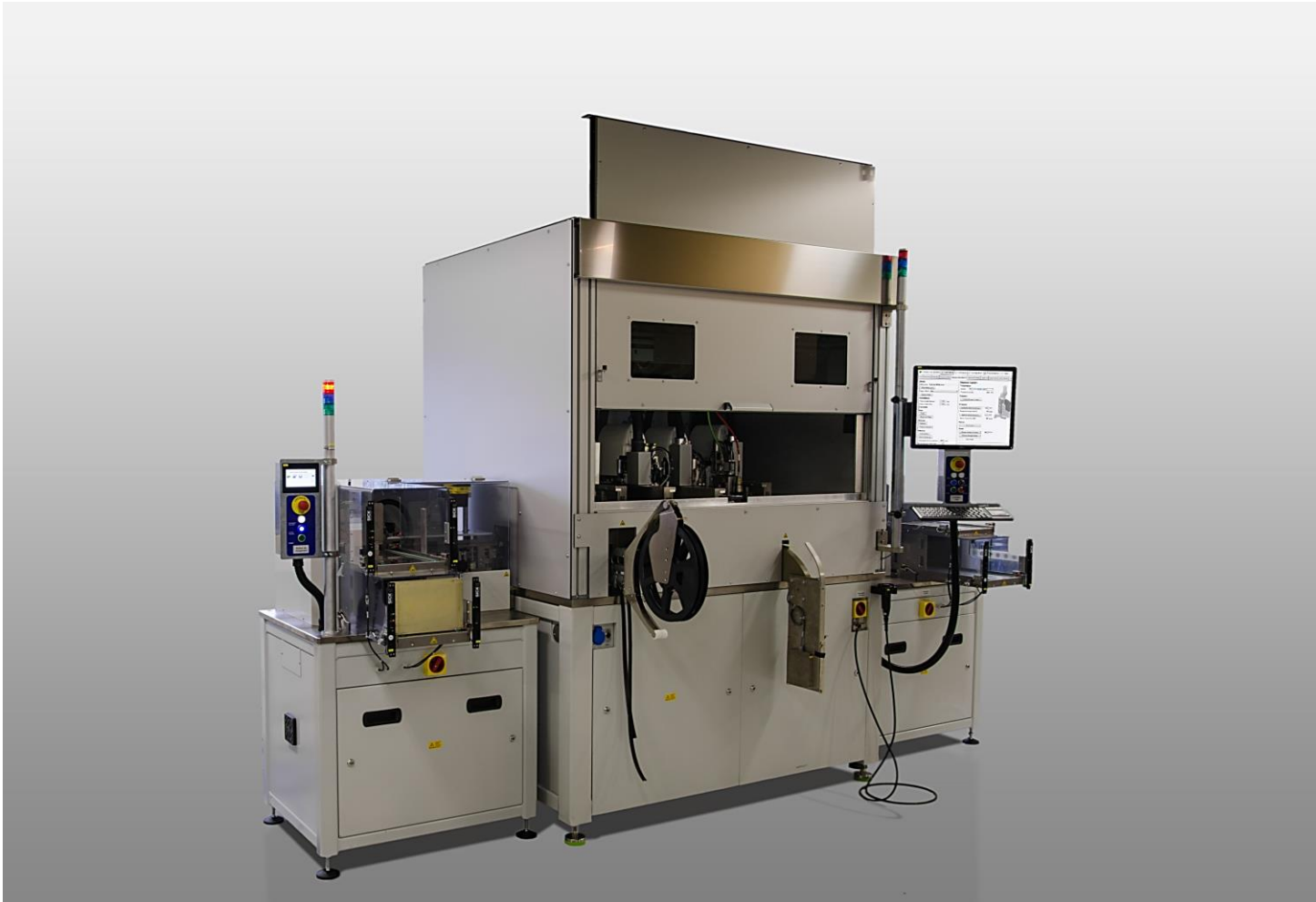
Precision membrane assembly of a valve for asthma spray

## Pharmamontagelinie:

3X IC-1200 / 2x IP-520 / 4x IP-100

Präzision-Membranbestückung in einem Ventil für einen Asthmaspray

# FC-1600 WATCH PRODUCTION LINE



## Watch assembly (Swatch):

- 2X FC-1600 / 5X IP-100 / 1X IP-520
- Assembling and soldering of pcb onto leadframe  
Welding of quartz onto leadframe
- Cut, test and sort into output tray

## Uhrenmontage (Swatch):

- 2X FC-1600 / 5X IP-100 / 1X IP-520
- Bestücken und löten eines Elektronikbauteils
- Bestücken und schweissen eines Quarzes
- Schneiden, testen und ablegen in Ausgangstray

# WATCH ASSEMBLY LINE



28 IC-1000 / 28 IP-520 / 10 IP-100 SWATCH  
SYSTEM51

First fully automatic production line with  
complete assembly and functional test of  
mechanical watch SYSTEM51 of Swatch

Erste vollautomatisch Produktionslinie zur  
vollständigen Montage des mechanischen  
Uhrwerks SYSTEM51 von Swatch



# DBC PRODUCTION LINE

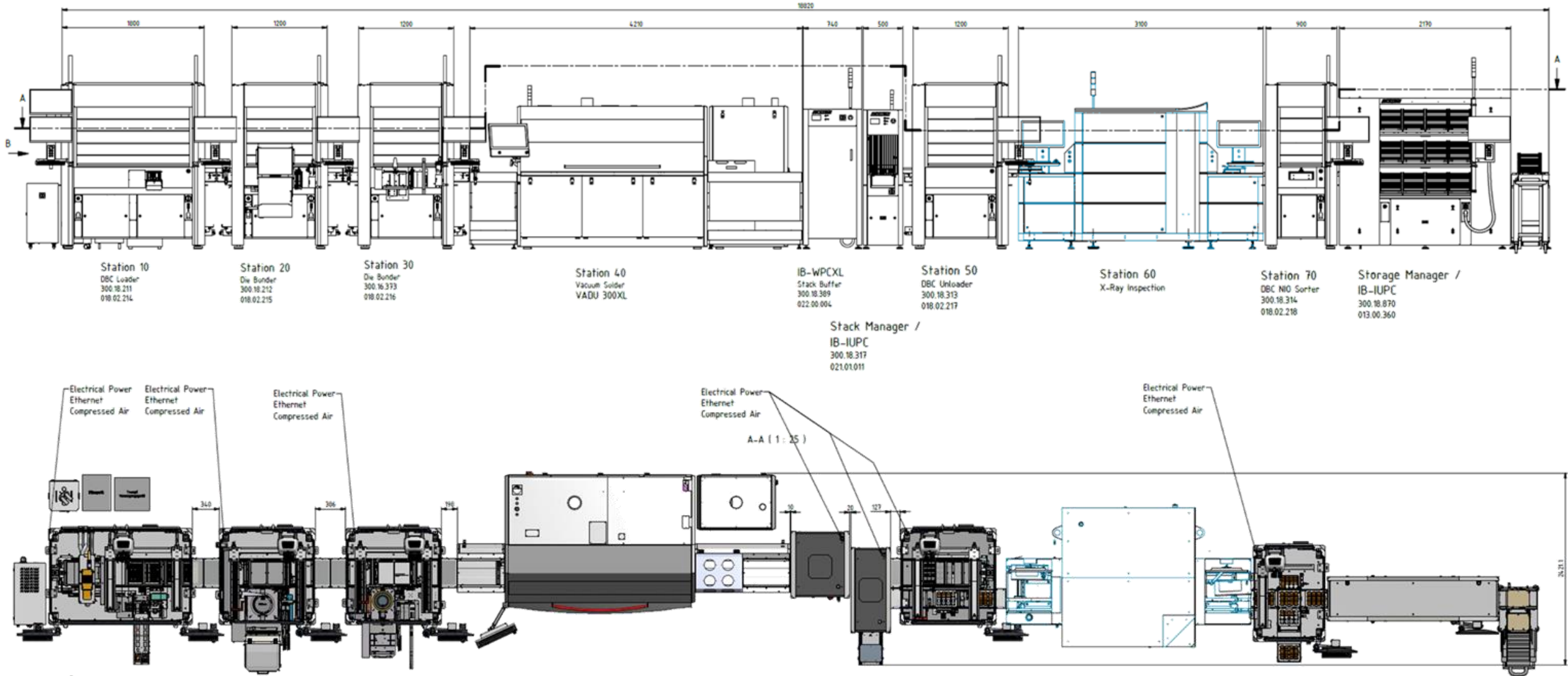


Fully automatic DBC production line using flux free soldering including laser marking, automatic material loading and unloading using AGV systems

Vollautomatische DBC (Substrat) Produktionsanlage zum flussmittelfreien Löten, mit Lasermarkierung und voll automatischem Material zu- und wegführen mittels AGV (Autonomous guided vehicles)



# TYPICAL POWER MODULE PRODUCTION LINE



# POWER DIODE PRODUCTION LINE



- Carrier lift to upper conveyor
- Heat sink mounter
- Preform attacher
- Die bonder
- Preform attacher
- Head wire mounter

- Vacuum oven

- Stacker
- Power diode unloader
- Carrier lift to lower conveyor
- Gel dispenser
- Electrical tester
- Unloader



***INFOTECH***  
*automation*

**Exceeding your expectations**